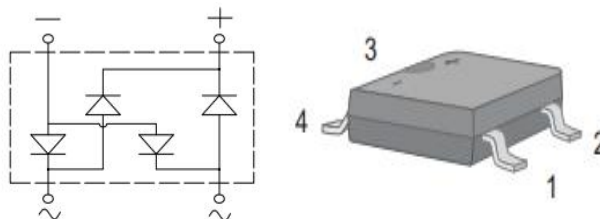


Bridge Rectifier Diode 整流桥

■ Features 特点

Glass passivated chip junction 玻璃钝化结
High surge current capability 高浪涌电流能力
Reflow Solder Temperature 220°C 回流焊温度 220 度
Package 封装: ABS



■ Maximum Rating 最大额定值

($T_A=25^{\circ}\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

| Characteristic 特性参数 | Symbol 符号 | ABS21 | ABS22 | ABS24 | ABS26 | ABS28 | ABS210 | Unit 单位 |
|---|-----------------|---|-------|-------|-------|-------|--------|-----------------------------|
| Peak Reverse Voltage 反向峰值电压 | V_{RRM} | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| DC Reverse Voltage 直流反向电压 | $V_{R(DC)}$ | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| RMS Reverse Voltage 反向电压均方根值 | $V_{R(RMS)}$ | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Forward Rectified Current 正向整流电流 | I_F | 2 | | | | | | A |
| Peak Surge Current 峰值浪涌电流 | I_{FSM} | 50 | | | | | | A |
| Thermal Resistance J-A 结到环境热阻 | $R_{\theta JA}$ | 75 | | | | | | $^{\circ}\text{C}/\text{W}$ |
| Junction and Storage Temperature 结温和储藏温度 | T_J, T_{stg} | 150 $^{\circ}\text{C}$, -55to+150 $^{\circ}\text{C}$ | | | | | | |

■ Electrical Characteristics 电特性

($T_A=25^{\circ}\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

| Characteristic 特性参数 | Symbol 符号 | Min 最小值 | Typ 典型值 | Max 最大值 | Unit 单位 | Condition 条件 |
|--|-----------|---------|---------|----------|---------------|--------------------------------|
| Forward Voltage 正向电压降 | V_F | | 1 | | V | $I_F=1\text{A}$ |
| Reverse Current ($T_A=25^{\circ}\text{C}$) 反向漏电流($T_A=125^{\circ}\text{C}$) | I_R | | | 5 500 | μA | $V_R=V_{RRM}$ |
| Diode Capacitance 二极管电容 | C_D | | 18 | | pF | $V_R=4\text{V}, f=1\text{MHz}$ |

■ Typical Characteristic Curve 典型特性曲线

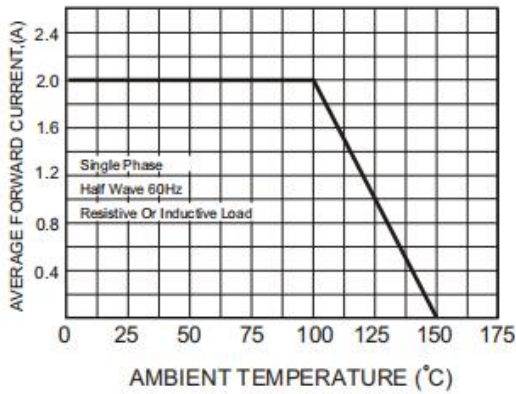


Figure 1: Forward Current Derating Curve

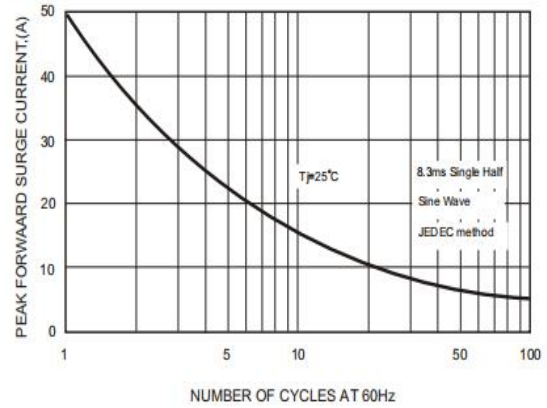


Figure 2: Peak Forward Surge Current

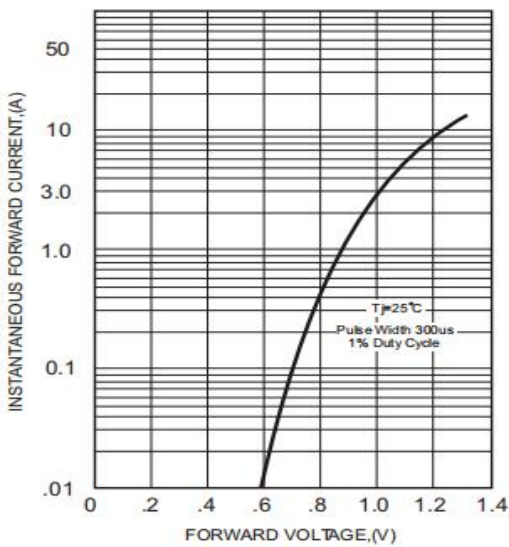


Figure 3: Instantaneous Forward Characteristics

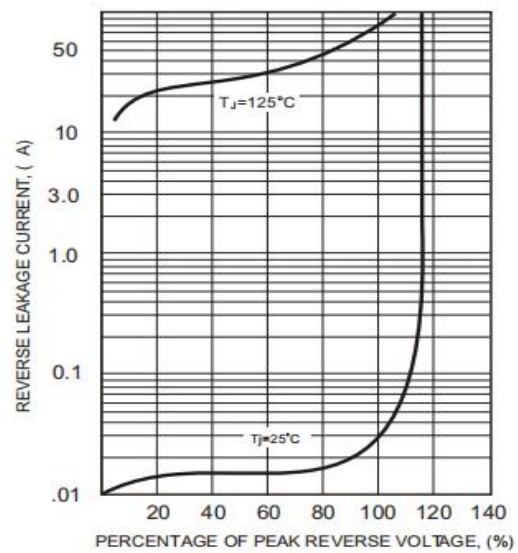
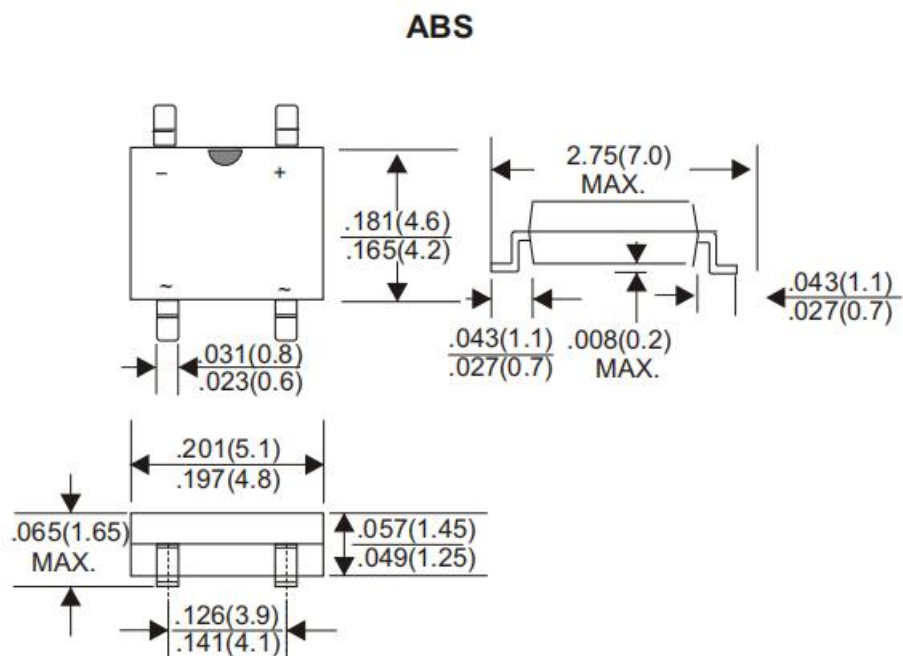


Figure 4: Reverse Leakage Characteristics

■Dimension 外形封装尺寸



Dimensions in inches and (millimeters)